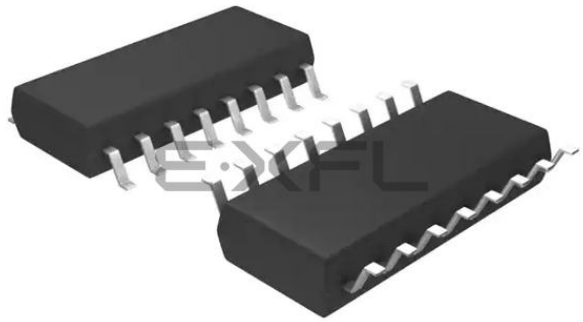

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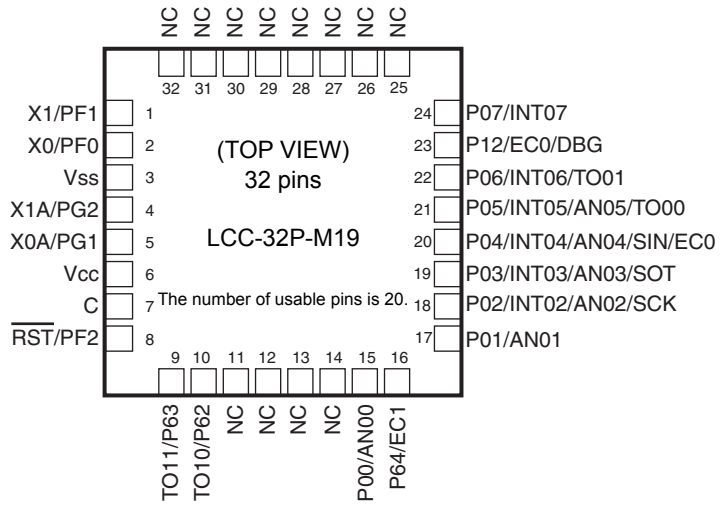
What is "Embedded - Microcontrollers"?

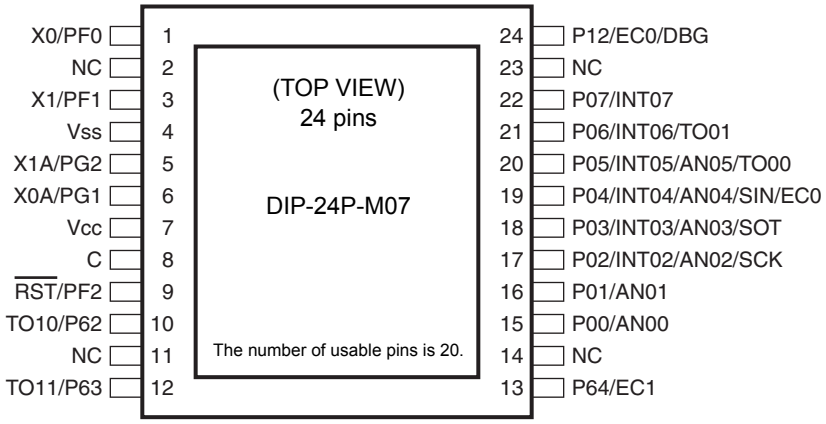
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

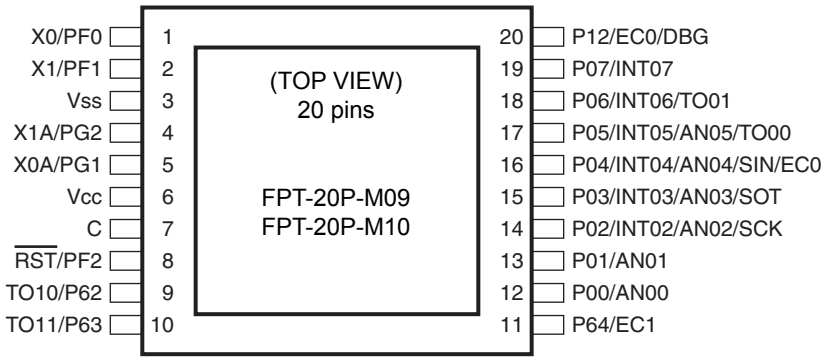
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	LINbus, SIO, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	240 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 5x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.209", 5.30mm Width)
Supplier Device Package	16-SOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f282kpf-g-sne1

4. Pin Assignment







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Pin no.	Pin name	I/O circuit type*	Function
18	P03	E	General-purpose I/O port
	INT03		External interrupt input pin
	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin
19	P04	F	General-purpose I/O port
	INT04		External interrupt input pin
	AN04		A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
20	P05	E	General-purpose I/O port High-current pin
	INT05		External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
21	P06	G	General-purpose I/O port High-current pin
	INT06		External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
22	P07	G	General-purpose I/O port
	INT07		External interrupt input pin
23	NC	—	It is an internally connected pin. Always leave it unconnected.
24	P12	H	General-purpose I/O port
	EC0		8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

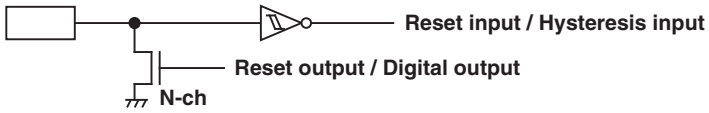
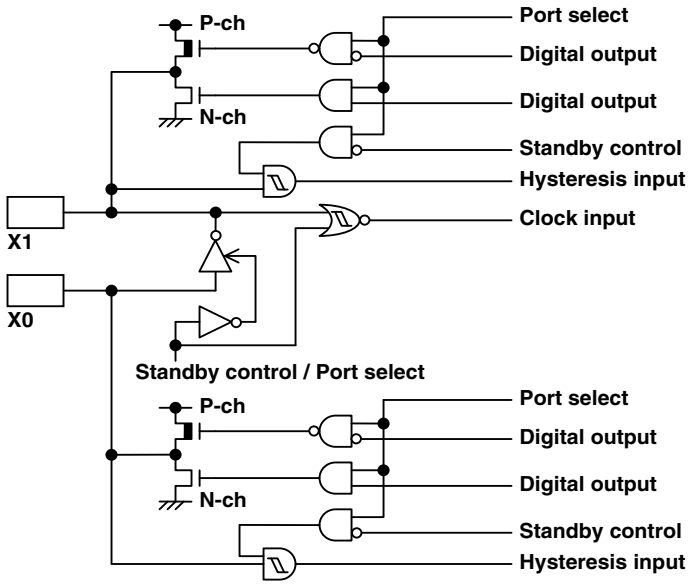
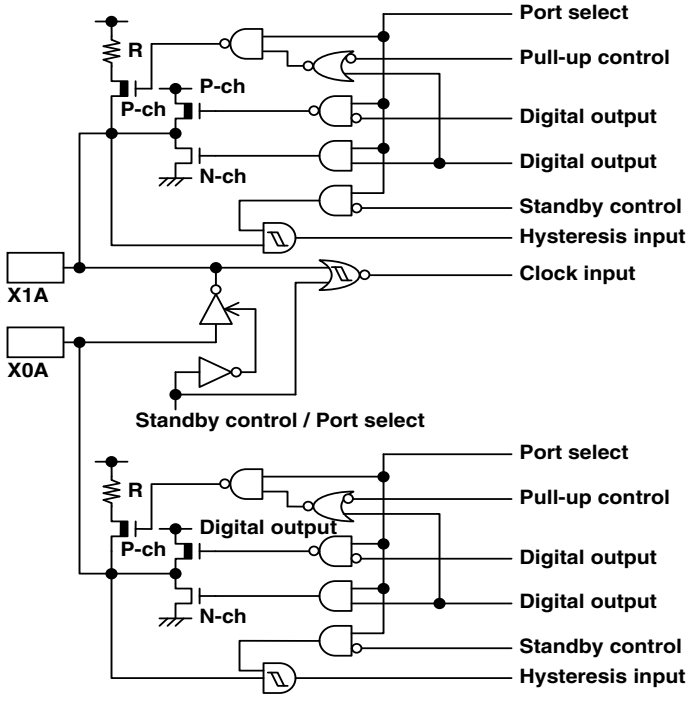
*: For the I/O circuit types, see “11. I/O Circuit Type”.

7. Pin Description (MB95260H Series, 20 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	PF0	B	General-purpose I/O port
	X0		Main clock input oscillation pin
2	PF1	B	General-purpose I/O port
	X1		Main clock I/O oscillation pin
3	V_{SS}	—	Power supply pin (GND)
4	PG2	C	General-purpose I/O port
	X1A		Subclock I/O oscillation pin
5	PG1	C	General-purpose I/O port
	X0A		Subclock input oscillation pin
6	V_{CC}	—	Power supply pin
7	C	—	Capacitor connection pin
8	PF2	A	General-purpose I/O port
	$\overline{RST}$		Reset pin This is a dedicated reset pin in MB95F262H/F263H/F264H.
9	P62	D	General-purpose I/O port High-current pin
	TO10		8/16-bit composite timer ch. 1 output pin
10	P63	D	General-purpose I/O port High-current pin
	TO11		8/16-bit composite timer ch. 1 output pin
11	P64	D	General-purpose I/O port
	EC1		8/16-bit composite timer ch. 1 clock input pin
12	P00	E	General-purpose I/O port
	AN00		A/D converter analog input pin
13	P01	E	General-purpose I/O port
	AN01		A/D converter analog input pin
14	P02	E	General-purpose I/O port
	INT02		External interrupt input pin
	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
15	P03	E	General-purpose I/O port
	INT03		External interrupt input pin
	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin

(Continued)

11. I/O Circuit Type

Type	Circuit	Remarks
A		• N-ch open drain output • Hysteresis input • Reset output
B		• Oscillation circuit • High-speed side • Feedback resistance: approx. 1 MΩ • CMOS output • Hysteresis input
C		• Oscillation circuit • Low-speed side • Feedback resistance: approx.10 MΩ • CMOS output • Hysteresis input • Pull-up control available

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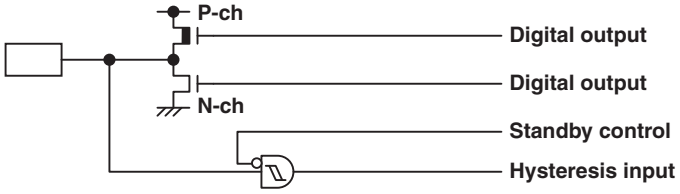
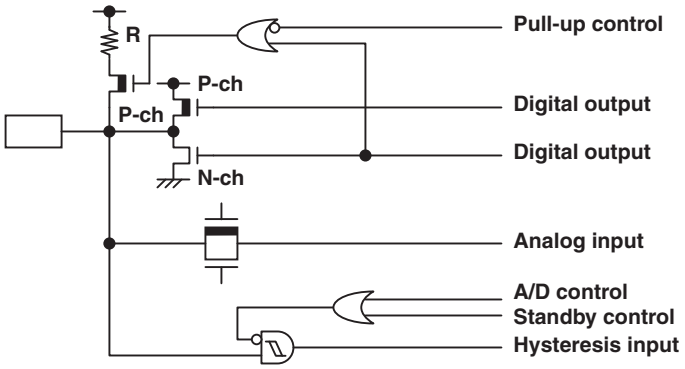
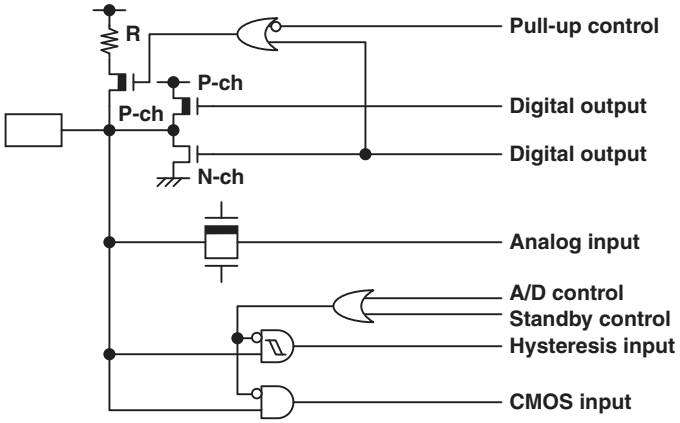
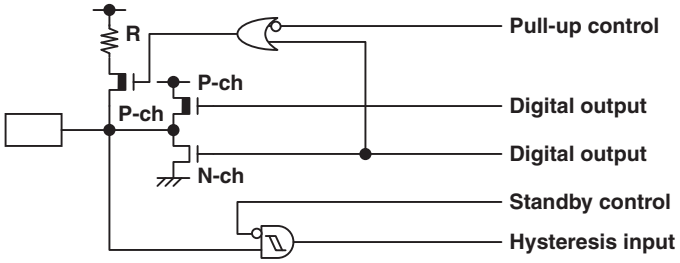
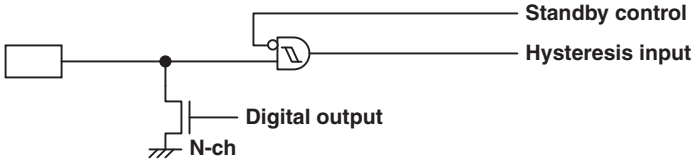
Type	Circuit	Remarks
D		• CMOS output • Hysteresis input
E		• CMOS output • Hysteresis input • Pull-up control available
F		• CMOS output • Hysteresis input • CMOS input • Pull-up control available
G		• Hysteresis input • CMOS output • Pull-up control available
H		• N-ch open drain output • Hysteresis input

12. Notes on Device Handling

Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.

In a CMOS IC, if a voltage higher than V_{CC} or a voltage lower than V_{SS} is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in “24.1 Absolute Maximum Ratings” of “24. Electrical Characteristics” is applied to the V_{CC} pin or the V_{SS} pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

Stabilizing supply voltage

Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the V_{CC} power supply voltage.

As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{CC} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{CC} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

13. Pin Connection

Treatment of unused pins

If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latch-ups. Always pull up or pull down an unused input pin through a resistor of at least 2 kΩ. Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{CC} pin and the V_{SS} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{CC} pin and the V_{SS} pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 µF as a bypass capacitor between the V_{CC} pin and the V_{SS} pin at a location close to this device.

DBG pin

Connect the DBG pin directly to an external pull-up resistor.

To prevent the device from unintentionally entering the debug mode due to noise, minimize the distance between the DBG pin and the V_{CC} or V_{SS} pin when designing the layout of the printed circuit board.

The DBG pin should not stay at “L” level after power-on until the reset output is released.

$\overline{\text{RST}}$ pin

Connect the $\overline{\text{RST}}$ pin directly to an external pull-up resistor.

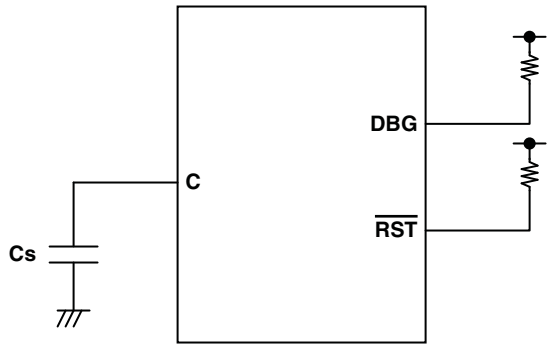
To prevent the device from unintentionally entering the reset mode due to noise, minimize the distance between the $\overline{\text{RST}}$ pin and the V_{CC} or V_{SS} pin when designing the layout of the printed circuit board.

The PF2/$\overline{\text{RST}}$ pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/$\overline{\text{RST}}$ pin can be enabled by the RSTOE bit of the SYSC register, and the reset input function and the general purpose I/O function can be selected by the RSTEN bit of the SYSC register.

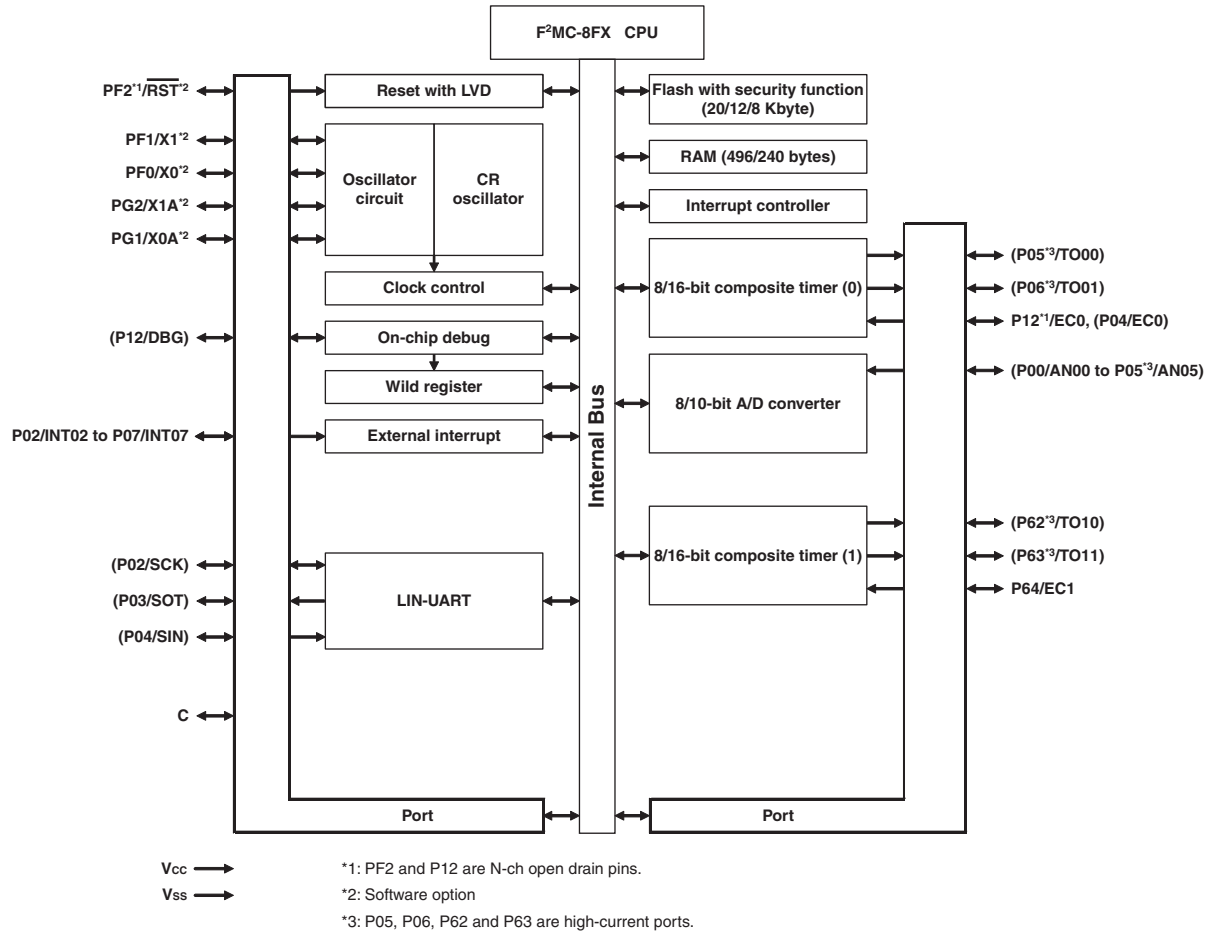
C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The bypass capacitor for the V_{CC} pin must have a capacitance larger than C_S. For the connection to a smoothing capacitor C_S, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

DBG/$\overline{\text{RST}}$/C pins connection diagram

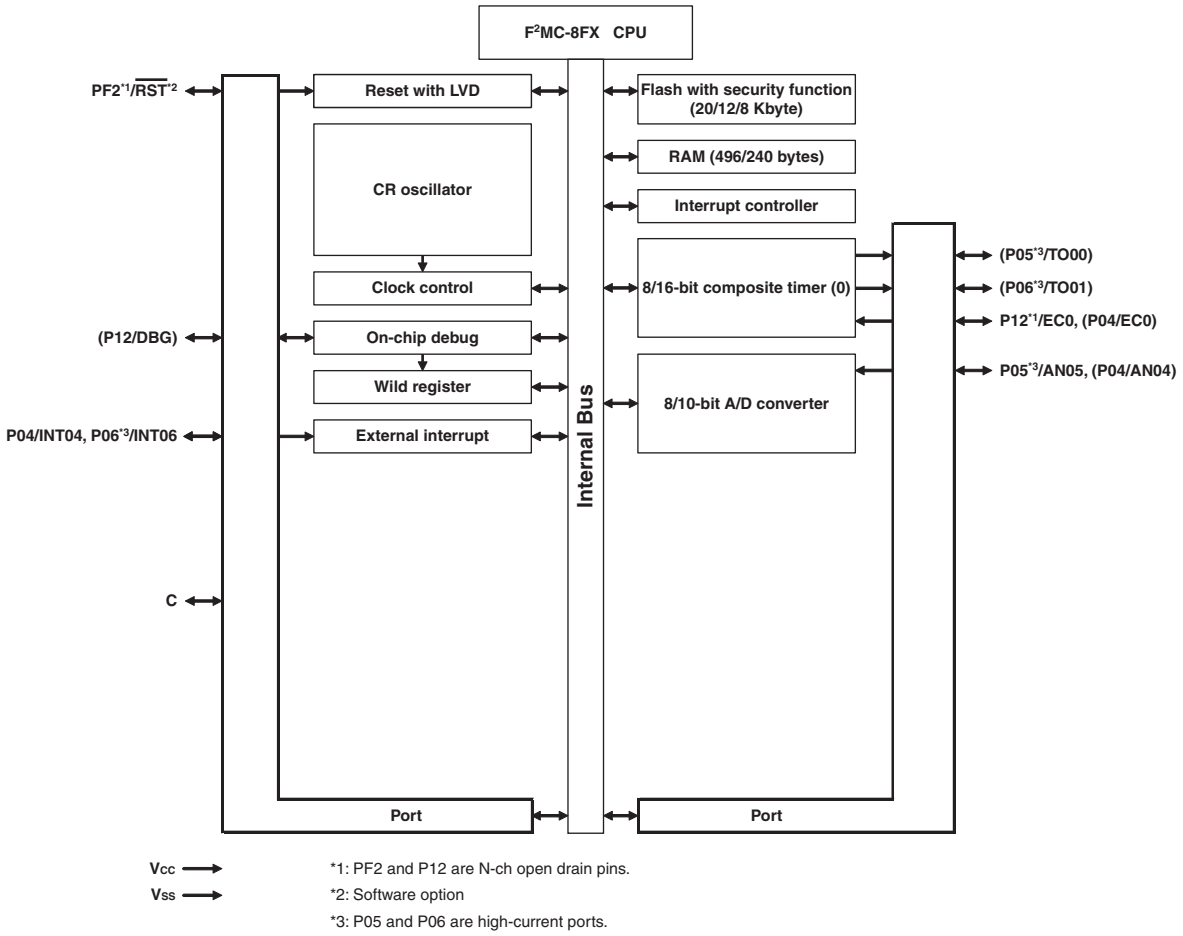


14. Block Diagram (MB95260H Series)



Note: Pins in parentheses indicate that functions of those pins are shared among different resources.

15. Block Diagram (MB95270H Series)



Note: Pins in parentheses indicate that functions of those pins are shared among different resources.

22. Interrupt Source Table (MB95270H Series)

Interrupt source	Interrupt request number	Vector table address		Bit name of interrupt level setting register	Priority order of interrupt sources of the same level (occurring simultaneously)
		Upper	Lower		
External interrupt ch. 4	IRQ00	$FFFA_H$	$FFFB_H$	L00 [1:0]	High
—	IRQ01	$FFF8_H$	$FFF9_H$	L01 [1:0]	
—	IRQ02	$FFF6_H$	$FFF7_H$	L02 [1:0]	
External interrupt ch. 6					
—	IRQ03	$FFF4_H$	$FFF5_H$	L03 [1:0]	
—					
—	IRQ04	$FFF2_H$	$FFF3_H$	L04 [1:0]	
8/16-bit composite timer ch. 0 (Lower)	IRQ05	$FFF0_H$	$FFF1_H$	L05 [1:0]	
8/16-bit composite timer ch. 0 (Upper)	IRQ06	$FFEE_H$	$FFEF_H$	L06 [1:0]	
—	IRQ07	$FFEC_H$	$FFED_H$	L07 [1:0]	
—	IRQ08	$FFEA_H$	$FFEB_H$	L08 [1:0]	
—	IRQ09	$FFE8_H$	$FFE9_H$	L09 [1:0]	
—	IRQ10	$FFE6_H$	$FFE7_H$	L10 [1:0]	
—	IRQ11	$FFE4_H$	$FFE5_H$	L11 [1:0]	
—	IRQ12	$FFE2_H$	$FFE3_H$	L12 [1:0]	
—	IRQ13	$FFE0_H$	$FFE1_H$	L13 [1:0]	
—	IRQ14	$FFDE_H$	$FFDF_H$	L14 [1:0]	
—	IRQ15	$FFDC_H$	$FFDD_H$	L15 [1:0]	
—	IRQ16	$FFDA_H$	$FFDB_H$	L16 [1:0]	
—	IRQ17	$FFD8_H$	$FFD9_H$	L17 [1:0]	
8/10-bit A/D converter	IRQ18	$FFD6_H$	$FFD7_H$	L18 [1:0]	
Time-base timer	IRQ19	$FFD4_H$	$FFD5_H$	L19 [1:0]	
Watch prescaler	IRQ20	$FFD2_H$	$FFD3_H$	L20 [1:0]	
—	IRQ21	$FFD0_H$	$FFD1_H$	L21 [1:0]	
—	IRQ22	$FFCE_H$	$FFCF_H$	L22 [1:0]	
Flash memory	IRQ23	$FFCC_H$	$FFCD_H$	L23 [1:0]	Low

24.3 DC Characteristics

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to + 85°C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IHI}	P04	*1	0.7 V_{CC}	—	V_{CC} + 0.3	V	When CMOS input level (hysteresis input) is selected
	V_{IHS}	P00 to P07, P12, P62 to P64, PF0, PF1, PG1, PG2	*1	0.8 V_{CC}	—	V_{CC} + 0.3	V	Hysteresis input
	V_{IHM}	PF2	—	0.7 V_{CC}	—	V_{CC} + 0.3	V	Hysteresis input
"L" level input voltage	V_{IL}	P04	*1	V_{SS} - 0.3	—	0.3 V_{CC}	V	When CMOS input level (hysteresis input) is selected
	V_{ILS}	P00 to P07, P12, P62 to P64, PF0, PF1, PG1, PG2	*1	V_{SS} - 0.3	—	0.2 V_{CC}	V	Hysteresis input
	V_{ILM}	PF2	—	V_{SS} - 0.3	—	0.3 V_{CC}	V	Hysteresis input
Open-drain output application voltage	V_D	PF2, P12	—	V_{SS} - 0.3	—	V_{SS} + 5.5	V	
"H" level output voltage	V_{OH1}	Output pins other than P05, P06, P12, P62, P63, PF2*2	I_{OH} = - 4 mA	V_{CC} - 0.5	—	—	V	
	V_{OH2}	P05, P06, P62, P63*2	I_{OH} = - 8 mA	V_{CC} - 0.5	—	—	V	
"L" level output voltage	V_{OL1}	Output pins other than P05, P06, P62, P63*2	I_{OL} = 4 mA	—	—	0.4	V	
	V_{OL2}	P05, P06, P62, P63*2	I_{OL} = 12 mA	—	—	0.4	V	
Input leak current (Hi-Z output leak current)	I_{LI}	All input pins	0.0 V < V_I < V_{CC}	- 5	—	+ 5	µA	When pull-up resistance is disabled
Pull-up resistance	R_{PULL}	P00 to P07, PG1, PG2*3*4	V_I = 0 V	25	50	100	kΩ	When pull-up resistance is enabled
Input capacitance	C_{IN}	Other than V_{CC} and V_{SS}	f = 1 MHz	—	5	15	pF	

(Continued)

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to + 85°C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current*4	I_{CC}	V_{CC} (External clock operation)	V_{CC} = 5.5 V F_{CH} = 32 MHz F_{MP} = 16 MHz Main clock mode (divided by 2)	—	13	17	mA	Except during Flash memory programming and erasing
				—	33.5	39.5	mA	During Flash memory programming and erasing
				—	15	21	mA	At A/D conversion
	I_{CCS}		V_{CC} = 5.5 V F_{CH} = 32 MHz F_{MP} = 16 MHz Main sleep mode (divided by 2)	—	5.5	9	mA	
	I_{CCL}		V_{CC} = 5.5 V F_{CL} = 32 kHz F_{MPL} = 16 kHz Subclock mode (divided by 2) T_A = + 25°C	—	65	153	µA	
	I_{CCLS}		V_{CC} = 5.5 V F_{CL} = 32 kHz F_{MPL} = 16 kHz Subsleep mode (divided by 2) T_A = + 25°C	—	10	84	µA	
	I_{CCT}		V_{CC} = 5.5 V F_{CL} = 32 kHz Watch mode Main stop mode T_A = + 25°C	—	5	30	µA	
	I_{CCMCR}	V_{CC}	V_{CC} = 5.5 V F_{CRH} = 10 MHz F_{MP} = 10 MHz Main CR clock mode	—	8.6	—	mA	
	I_{CCSCR}		V_{CC} = 5.5 V Sub-CR clock mode (divided by 2) T_A = + 25°C	—	110	410	µA	

(Continued)

24.4.5 Peripheral Input Timing

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to + 85°C)

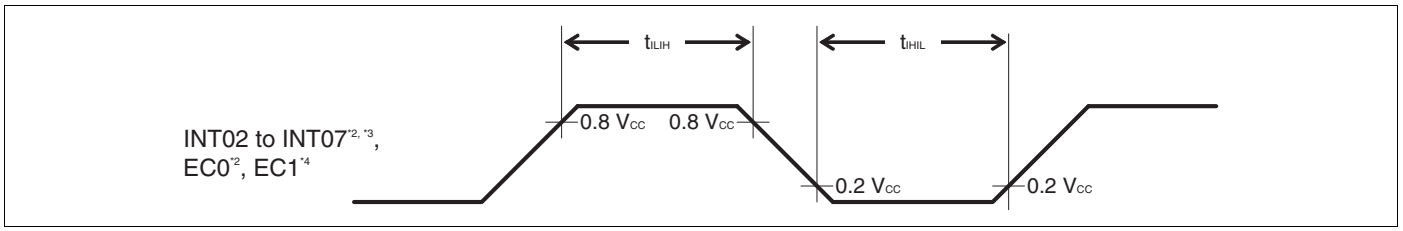
Parameter	Symbol	Pin name	Value		Unit
			Min	Max	
Peripheral input “H” pulse width	t_{ILIH}	INT02 to INT07*2,*3, EC0*2, EC1*4	2 t_{MCLK}*1	—	ns
Peripheral input “L” pulse width	t_{IHIL}		2 t_{MCLK}*1	—	ns

*1: See “24.4.2. Source Clock / Machine Clock” for t_{MCLK}.

*2: INT04, INT06 and EC0 are available in all products.

*3: INT02, INT03, INT05 and INT07 are only available on MB95F262H/F262K/F263H/F263K/F264H/F264K/F282H/F282K/F283H /F283K/F284H/F284K.

*4: EC1 is only available on MB95F262H/F262K/F263H/F263K/F264H/F264K.



24.4.6 LIN-UART Timing (only available on MB95F262H/F262K/F263H/F263K/F264H/F264K/F282H/F282K/F283H/F283K/F284H /F284K)

*Sampling is executed at the rising edge of the sampling clock*1, and serial clock delay is disabled*2.*
(ESCR register: SCES bit = 0, ECCR register: SCDE bit = 0)

(V_{CC} = 5.0 V±10%, AV_{SS} = V_{SS} = 0.0 V, T_A = -40°C to + 85°C)

Parameter	Symbol	Pin name	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin: C_L = 80 pF + 1 TTL	5 t_{MCLK}*3	—	ns
SCK ↓→ SOT delay time	t_{SLOVI}	SCK, SOT		- 95	+ 95	ns
Valid SIN → SCK ↑	t_{IVSHI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK ↑→ valid SIN hold time	t_{SHIXI}	SCK, SIN		0	—	ns
Serial clock “L” pulse width	t_{SLSH}	SCK	External clock operation output pin: C_L = 80 pF + 1 TTL	3 t_{MCLK}*3 - t_R	—	ns
Serial clock “H” pulse width	t_{SHSL}	SCK		t_{MCLK}*3 + 95	—	ns
SCK ↓→ SOT delay time	t_{SLOVE}	SCK, SOT		—	2 t_{MCLK}*3 + 95	ns
Valid SIN → SCK ↑	t_{IVSHE}	SCK, SIN		190	—	ns
SCK ↑→ valid SIN hold time	t_{SHIXE}	SCK, SIN		t_{MCLK}*3 + 95	—	ns
SCK fall time	t_F	SCK		—	10	ns
SCK rise time	t_R	SCK		—	10	ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See “24.4.2. Source Clock / Machine Clock” for t_{MCLK}.

*Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is disabled*2.*
(ESCR register: SCES bit = 1, ECCR register: SCDE bit = 0)

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = -40°C to + 85°C)

Parameter	Symbol	Pin name	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin: C_L = 80 pF + 1 TTL	5 t_{MCLK}*3	—	ns
SCK ↑→ SOT delay time	t_{SHOVI}	SCK, SOT		- 95	+ 95	ns
Valid SIN → SCK ↓	t_{IVSLI}	SCK, SIN		t_{MCLK}*3 + 190	—	ns
SCK ↓→ valid SIN hold time	t_{SLIXI}	SCK, SIN		0	—	ns
Serial clock “H” pulse width	t_{SHSL}	SCK	External clock operation output pin: C_L = 80 pF + 1 TTL	3 t_{MCLK}*3 - t_R	—	ns
Serial clock “L” pulse width	t_{SLSH}	SCK		t_{MCLK}*3 + 95	—	ns
SCK ↑→ SOT delay time	t_{SHOVE}	SCK, SOT		—	2 t_{MCLK}*3 + 95	ns
Valid SIN → SCK↓	t_{IVSLE}	SCK, SIN		190	—	ns
SCK ↓→ valid SIN hold time	t_{SLIXE}	SCK, SIN		t_{MCLK}*3 + 95	—	ns
SCK fall time	t_F	SCK		—	10	ns
SCK rise time	t_R	SCK		—	10	ns

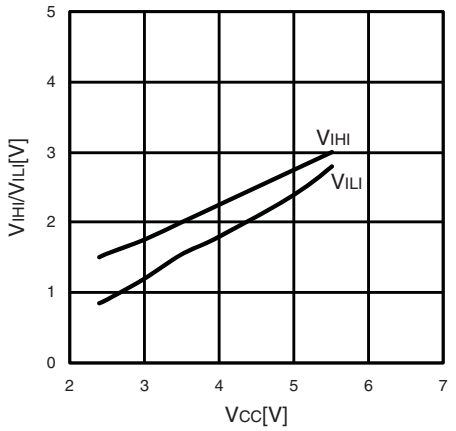
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

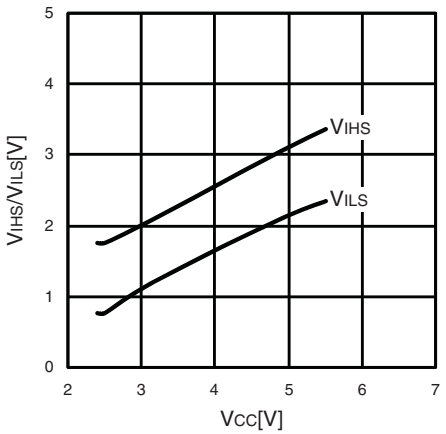
*3: See “24.4.2. Source Clock / Machine Clock” for t_{MCLK}.

Input voltage

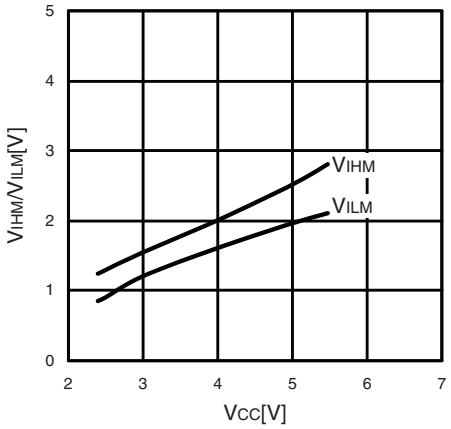
VIHI - VCC and VILI - VCC
TA=+25°C



VIHS - VCC and VILS - VCC
TA=+25°C



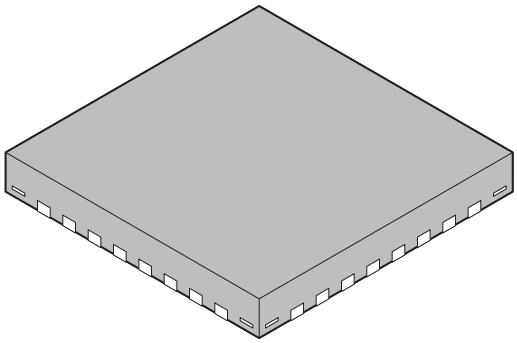
VIHM - VCC and VILM - VCC
TA=+25°C



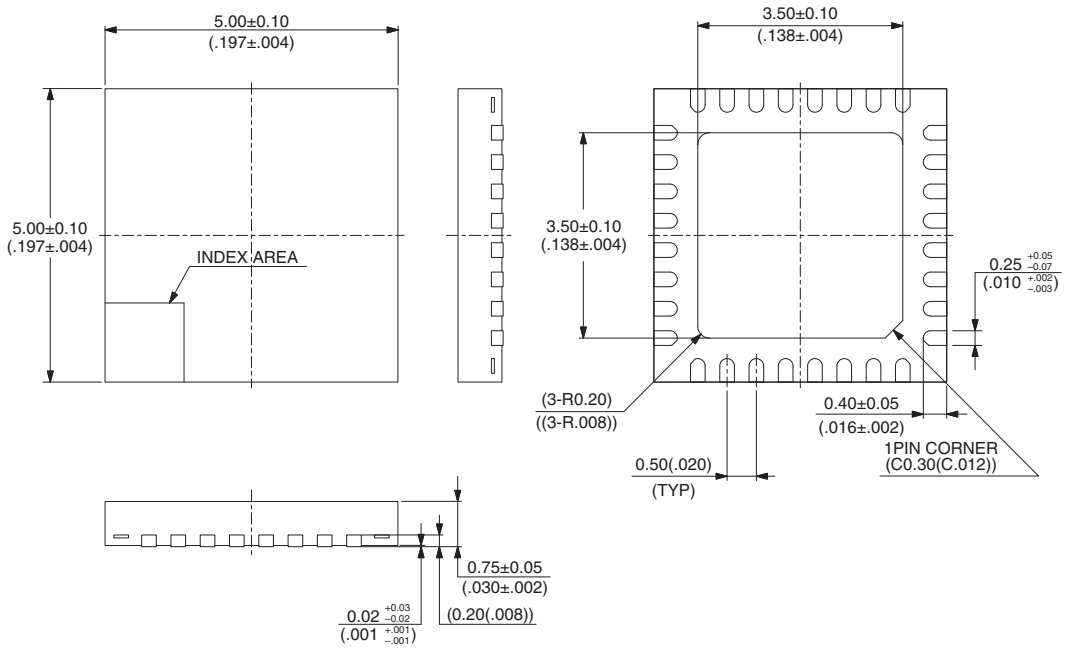
27. Ordering Information

Part Number	Package
MB95F262HWQN-G-SNE1 MB95F262HWQN-G-SNERE1 MB95F262KWQN-G-SNE1 MB95F262KWQN-G-SNERE1 MB95F263HWQN-G-SNE1 MB95F263HWQN-G-SNERE1 MB95F263KWQN-G-SNE1 MB95F263KWQN-G-SNERE1 MB95F264HWQN-G-SNE1 MB95F264HWQN-G-SNERE1 MB95F264KWQN-G-SNE1 MB95F264KWQN-G-SNERE1	32-pin plastic QFN (LCC-32P-M19)
MB95F262HP-G-SH-SNE2 MB95F262KP-G-SH-SNE2 MB95F263HP-G-SH-SNE2 MB95F263KP-G-SH-SNE2 MB95F264HP-G-SH-SNE2 MB95F264KP-G-SH-SNE2	24-pin plastic SDIP (DIP-24P-M07)
MB95F262HPF-G-SNE2 MB95F262KPF-G-SNE2 MB95F263HPF-G-SNE2 MB95F263KPF-G-SNE2 MB95F264HPF-G-SNE2 MB95F264KPF-G-SNE2	20-pin plastic SOP (FPT-20P-M09)
MB95F262HPFT-G-SNE2 MB95F262KPFT-G-SNE2 MB95F263HPFT-G-SNE2 MB95F263KPFT-G-SNE2 MB95F264HPFT-G-SNE2 MB95F264KPFT-G-SNE2	20-pin plastic TSSOP (FPT-20P-M10)
MB95F282HWQN-G-SNE1 MB95F282HWQN-G-SNERE1 MB95F282KWQN-G-SNE1 MB95F282KWQN-G-SNERE1 MB95F283HWQN-G-SNE1 MB95F283HWQN-G-SNERE1 MB95F283KWQN-G-SNE1 MB95F283KWQN-G-SNERE1 MB95F284HWQN-G-SNE1 MB95F284HWQN-G-SNERE1 MB95F284KWQN-G-SNE1 MB95F284KWQN-G-SNERE1	32-pin plastic QFN (LCC-32P-M19)
MB95F282HPH-G-SNE2 MB95F282KPH-G-SNE2 MB95F283HPH-G-SNE2 MB95F283KPH-G-SNE2 MB95F284HPH-G-SNE2 MB95F284KPH-G-SNE2	16-pin plastic DIP (DIP-16P-M06)

(Continued)

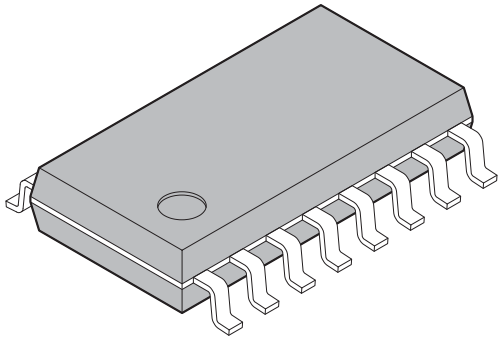
32-pin plastic QFN		
	Lead pitch	0.50 mm
	Package width × package length	5.00 mm × 5.00 mm
	Sealing method	Plastic mold
	Mounting height	0.80 mm MAX
	Weight	0.06 g
(LCC-32P-M19)		

32-pin plastic QFN
(LCC-32P-M19)



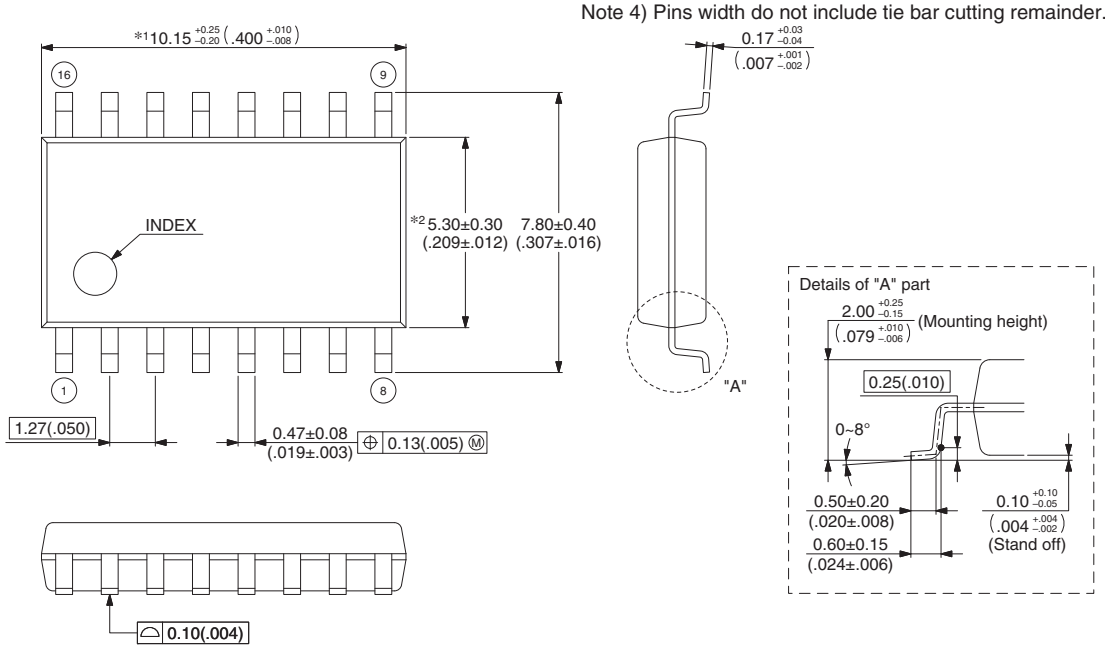
Dimensions in mm (inches).
Note: The values in parentheses are reference values.

(Continued)

16-pin plastic SOP		
	Lead pitch	1.27 mm
	Package width × package length	5.3 × 10.15 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	2.25 mm MAX
	Weight	0.20 g
(FPT-16P-M06)	Code (Reference)	P-SOP16-5.3×10.15-1.27

16-pin plastic SOP
(FPT-16P-M06)

Note 1) *1 : These dimensions include resin protrusion.
Note 2) *2 : These dimensions do not include resin protrusion.
Note 3) Pins width and pins thickness include plating thickness.
Note 4) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values.

(Continued)